2SK1608

Silicon N-Channel Power F-MOS FET

Features

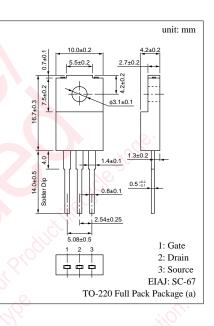
- High avalanche energy capacity
- V_{GSS}: 30V guaranteed
- \bullet Low R_{DS(on)}, high-speed switching characteristic

Applications

- High-speed switching (switching power supply)
- For high-frequency power amplification

Absolute Maximum Ratings ($T_C = 25^{\circ}C$)

Parameter		Symbol	Ratings	Unit	
Drain to Source breakdown voltage		V _{DSS}	500	V	
Gate to Source voltage		V _{GSS}	±30	V	
Drain current	DC	I _D	±5	Α	
	Pulse	I _{DP}	±10	Α	
Avalanche energy capacity		EAS*	100	mJ	
Allowable power	$T_C = 25^{\circ}C$	D	50	W	
dissipation	$Ta = 25^{\circ}C$	P _D 2		W	
Channel temperature		T _{ch}	150	°C	
Storage temperature		T _{stg}	-55 to +150	°C	

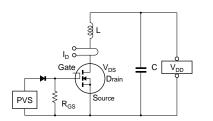


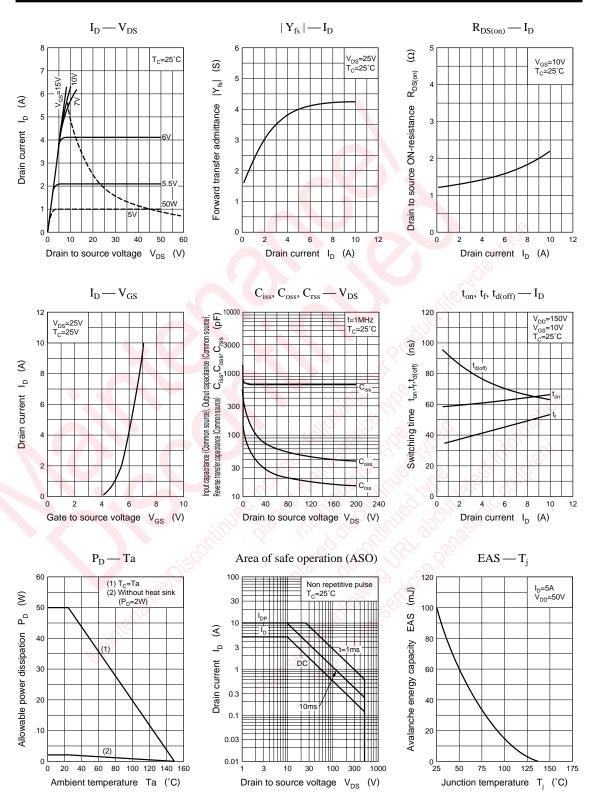
* Single pulse

Electrical Characteristics ($T_c = 25^{\circ}C$)

Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source cut-off current	I _{DSS}	$V_{\rm DS} = 400 V, V_{\rm GS} = 0$	N. C.	S ve	0.1	mA
Gate to Source leakage current	I _{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0$	EX 1		±1	μΑ
Drain to Source breakdown voltage	V _{DSS}	$I_D = 1mA, V_{GS} = 0$	500	55 60		V
Avalanche energy capacity	EAS*	$L = 8mH, I_D = 5A, V_{DD} = 50V$	100			mJ
Gate threshold voltage	V _{th}	$V_{DS} = 25V, I_D = 1mA$		SI'	5	v
Drain to Source ON-resistance	R _{DS(on)}	$V_{GS} = 10V, I_D = 3A$	2	1.35	1.7	Ω
Forward transfer admittance	Y _{fs}	$V_{DS} = 25V, I_D = 3A$	2	3.5		S
Input capacitance (Common Source)	C _{iss}		S),	700		pF
Output capacitance (Common Source)	C _{oss}	$V_{DS} = 20V, V_{GS} = 0, f = 1MHz$		100		pF
Reverse transfer capacitance (Common Source)	C _{rss}	is when		35		pF
Turn-on time	ton			60		ns
Fall time	t _f	$V_{GS} = 10V, I_D = 3A$		40		ns
Turn-off time (delay time)	t _{d(off)}	$V_{DD} = 150V, R_L = 50\Omega$		80		ns

^{*} Avalanche energy capacity test circuit





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